

Application No.: 10/788,756

Claims as Amended

The Applicant hereby elects Group I device claims 1-16 with traverse.

The Applicant hereby withdraws Claims 17-20 for further consideration by the Examiner.

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LISTING OF CLAIMS

1. (original) A particle-removing wafer, comprising:
 - a support body; and
 - a particle-adherent layer having a particle-adherent surface carried by said support body.
2. (original) The particle-removing wafer of claim 1 wherein said support body comprises a silicon wafer.
3. (original) The particle-removing wafer of claim 1 wherein said particle-adherent layer comprises a plastic polytetrafluoroethylene film.
4. (original) The particle-removing wafer of claim 3 wherein said support body comprises a silicon wafer.
5. (original) The particle-removing wafer of claim 1 further comprising an adhesive layer provided between said support body and said particle-adherent layer.
6. (original) The particle-removing wafer of claim 5 wherein said support body comprises a silicon wafer.
7. (original) The particle-removing wafer of claim 5 wherein said particle-adherent layer comprises a plastic polytetra-fluoroethylene film.

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8. (original) The particle-removing wafer of claim 7 wherein said support body comprises a silicon wafer.

9. (original) A particle-removing wafer, comprising:

a support body;

a resilient layer carried by said support body;

an adhesive layer carried by said resilient layer; and

a particle-adherent layer having a particle-adherent surface carried by said adhesive layer.

10. (original) The particle-removing wafer of claim 9 wherein said support body comprises a silicon wafer.

11. (original) The particle-removing wafer of claim 9 wherein said particle-adherent layer comprises a plastic polytetra-fluoroethylene film.

12. (original) The particle-removing wafer of claim 11 wherein said support body comprises a silicon wafer.

13. (original) The particle-removing wafer of claim 9 wherein said adhesive layer comprises a pair of adhesive surfaces.

14. (original) The particle-removing wafer of claim 13 wherein said support body comprises a silicon wafer.

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15. (original) The particle-removing wafer of claim 13 wherein said particle-adherent layer comprises a plastic polytetra-fluoroethylene film.

16. (original) The particle-removing wafer of claim 15 wherein said support body comprises a silicon wafer.

17. (withdrawn) A method of removing particles from a surface, comprising the steps of:
providing a particle-removing wafer having a particle-adherent surface;
placing said particle-adherent surface into contact with the particles on the surface; and
removing said particle-removing wafer from the surface.

18. (withdrawn) The method of claim 17 wherein said particle-removing wafer comprises a support body and a particle-adherent layer carried by said support body, and wherein said particle-adherent surface is provided on said particle-adherent layer.

19. (withdrawn) The method of claim 18 wherein said support body comprises a silicon wafer.

20. (withdrawn) The method of claim 18 further comprising a resilient layer provided on said support body and an adhesive layer provided on said resilient layer, and wherein said particle-adherent layer is provided on said adhesive layer.